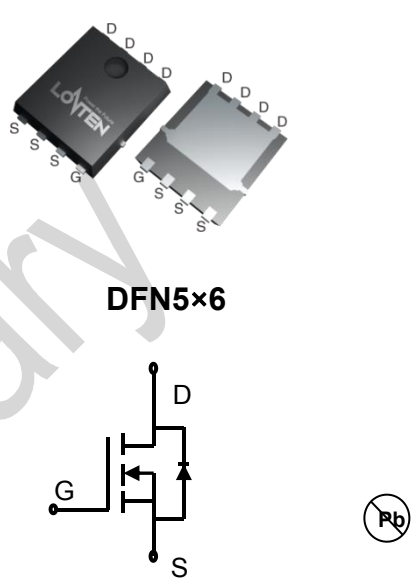


Lonten N-channel 100V, 82A, 4.5mΩ Power MOSFET

<p>Description</p> <p>These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.</p> <p>Features</p> <ul style="list-style-type: none"> ◆ 100V,82A, $R_{DS(on),max} = 4.5m\Omega @ V_{GS} = 10V$ ◆ Improved dv/dt capability ◆ Fast switching ◆ 100% EAS Guaranteed ◆ Green device available <p>Applications</p> <ul style="list-style-type: none"> ◆ MOTOR Driver ◆ BMS ◆ High frequency switching and synchronous rectification 	<p>Product Summary</p> <p>V_{DSS} 100V</p> <p>$R_{DS(on),max} @ V_{GS}=10V$ 4.5mΩ</p> <p>I_D 82A</p> <p>Pin Configuration</p>  <p style="text-align: center;">DFN5×6</p> <p style="text-align: center;">N-Channel MOSFET</p>
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Absolute Maximum Ratings $T_c = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	100	V
Continuous drain current ($T_c = 25^\circ\text{C}$) ($T_c = 100^\circ\text{C}$)	I_D	82	A
		61	A
Pulsed drain current ¹⁾	I_{DM}	246	A
Gate-Source voltage	V_{GSS}	± 20	V
Avalanche energy ²⁾	E_{AS}	7.2	mJ
Power Dissipation	P_D	78	W
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.6	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
LSGN10R045WB	DFN 5×6	10R045WB	5000

Electrical Characteristics
 $T_J = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	100	---	---	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2	3	4	V
Drain-source leakage current	I_{DSS}	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}$	---	---	1	μA
Gate leakage current, Forward	I_{GSSF}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	---	---	100	nA
Gate leakage current, Reverse	I_{GSSR}	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=13.5\text{ A}$	---	3.8	4.5	m Ω
Forward transconductance	g_{fs}	$V_{DS}=10\text{ V}, I_D=20\text{ A}$	---	50	---	S
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{DS}=50\text{ V}, V_{GS}=0\text{ V},$ $F=1\text{ MHz}$	---	4725	---	pF
Output capacitance	C_{oss}		---	609	---	
Reverse transfer capacitance	C_{rss}		---	14	---	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{ V}, V_{GS}=10\text{ V}, I_D=20\text{ A}$ $R_G=3\Omega$	---	35	---	ns
Rise time	t_r		---	18	---	
Turn-off delay time	$t_{d(off)}$		---	45	---	
Fall time	t_f		---	55	---	
Gate charge characteristics						
Gate to source charge	Q_{gs}	$V_{DS}=50\text{ V}, I_D=20\text{ A},$ $V_{GS}=10\text{ V}$	---	28	---	nC
Gate to drain charge	Q_{gd}		---	15	---	
Gate charge total	Q_g		---	74	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I_S		---	---	60	A
Pulsed Source Current ³⁾	I_{SM}		---	---	180	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0\text{ V}, I_S=13.5\text{ A}, T_J=25^\circ\text{C}$	---	---	1.3	V
Reverse recovery time	t_{rr}	$I_F=13.5\text{ A}, dI_F/dt=100\text{ A}/\mu\text{s}$	---	70	---	ns
Reverse recovery charge	Q_{rr}		---	170	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

 2: $V_{DD}=25\text{ V}, V_{GS}=10\text{ V}, L=0.1\text{ mH}, I_{AS}=12\text{ A}$, Starting $T_J=25^\circ\text{C}$.

 3: Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

Electrical Characteristics Diagrams

Fig 1. Typ. Output Characteristics

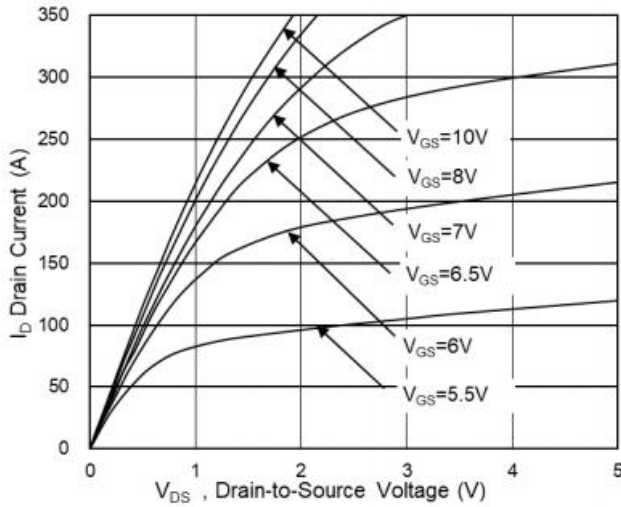


Fig 2. On-Resistance vs G-S Voltage

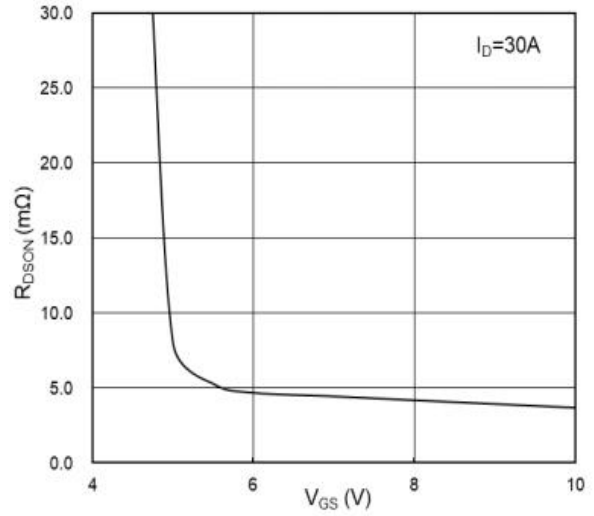


Fig 3. Capacitance Characteristics

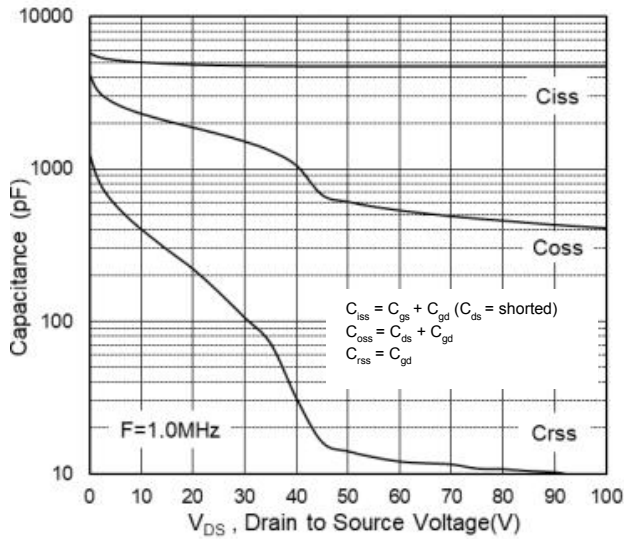


Figure 4. Gate Charge Waveform

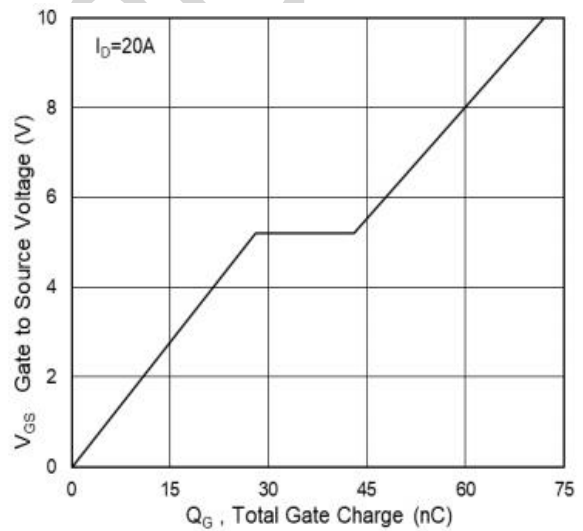


Fig 5. Body-Diode Characteristics

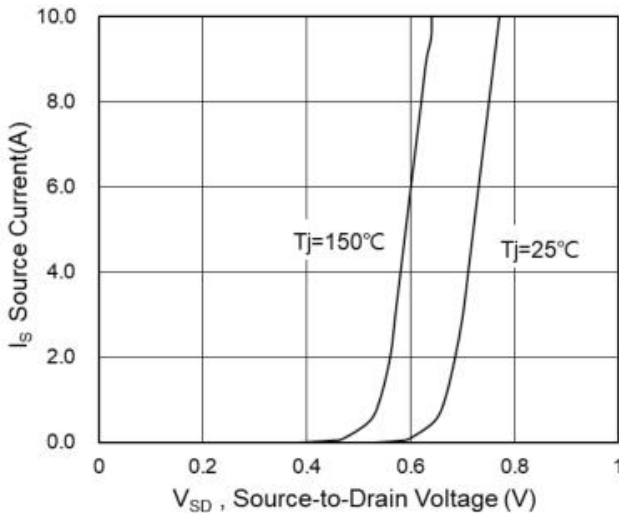


Fig 6. Rds(on)-Junction Temperature

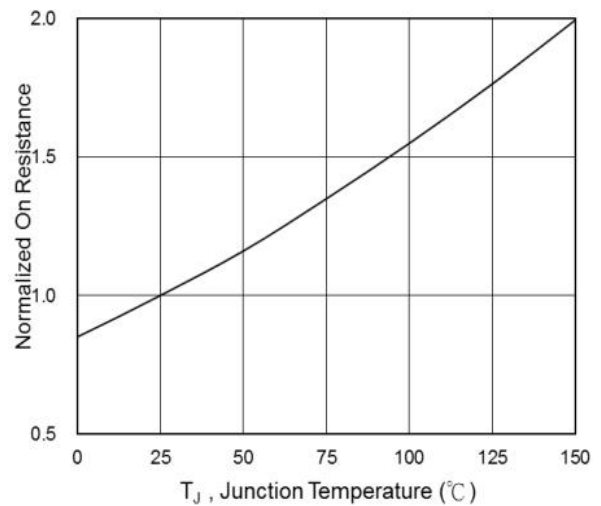


Fig 7. $V_{GS(th)}$ -Junction Temperature

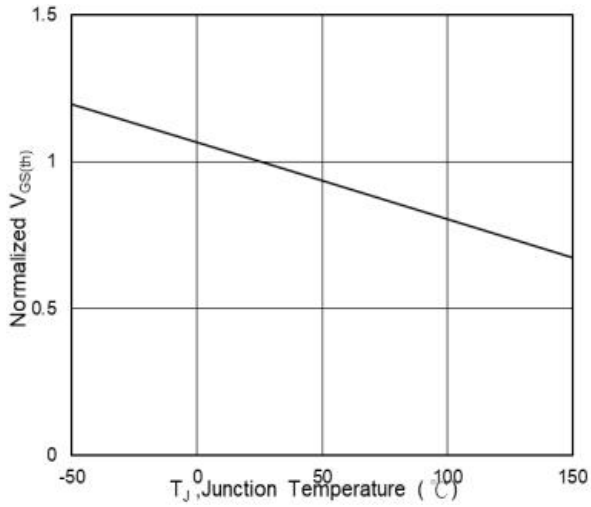


Fig 8: Safe Operating Area

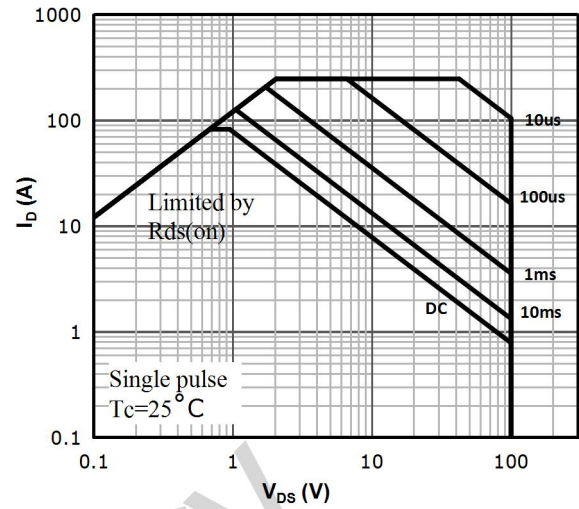
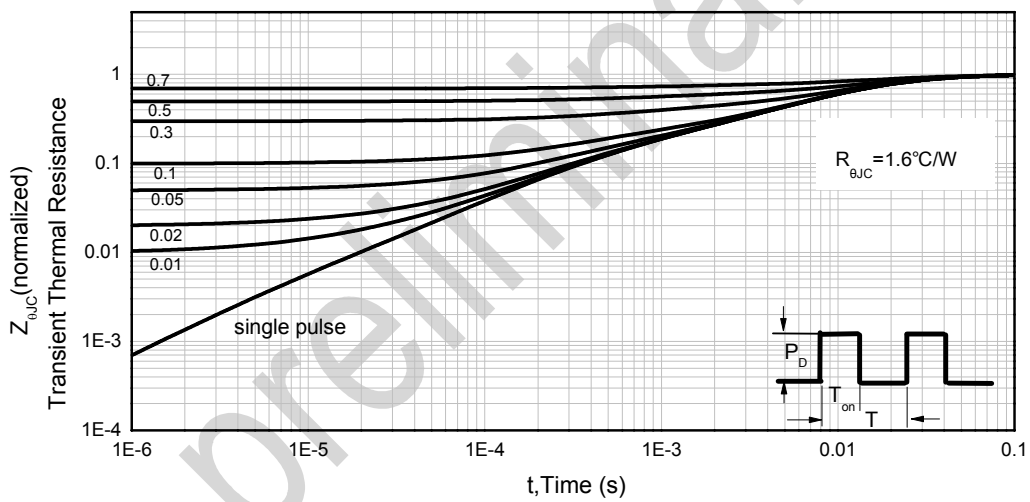
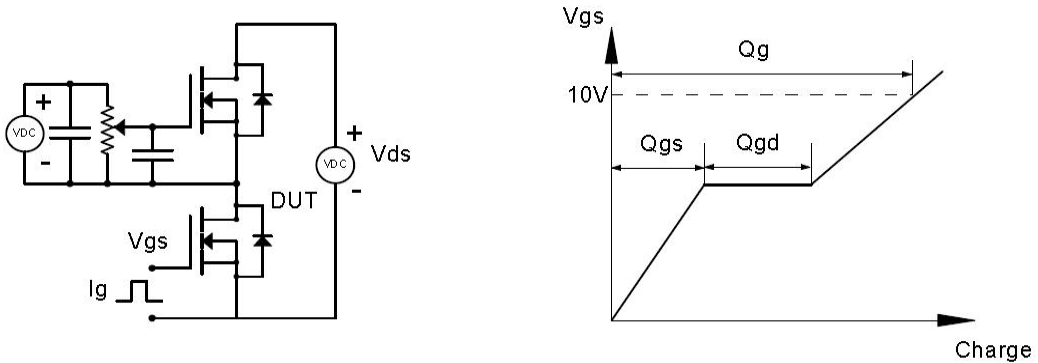


Fig 9. Normalized Maximum Transient Thermal Impedance (R_{thJC})

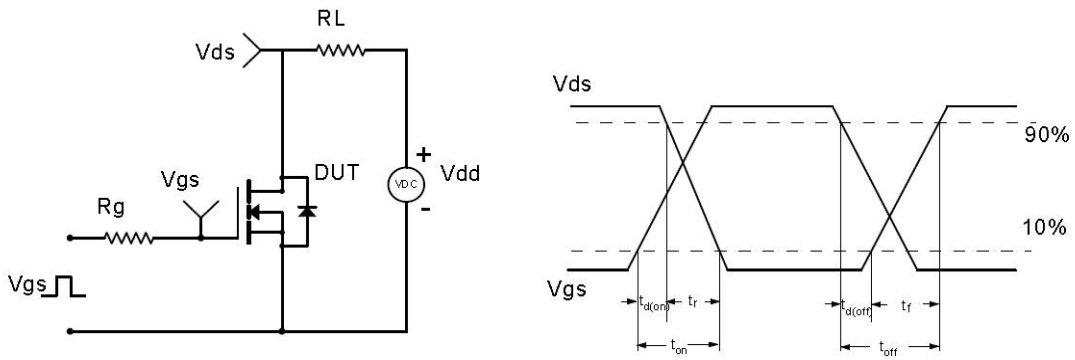


Test Circuit & Waveforms

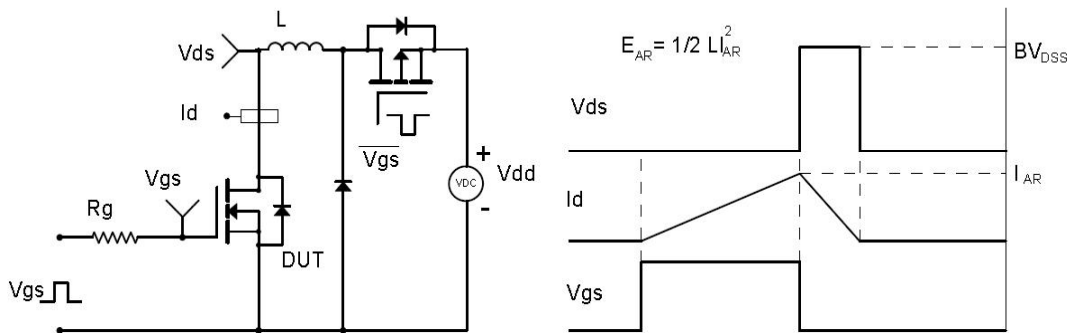
Gate Charge Test Circuit & Waveform



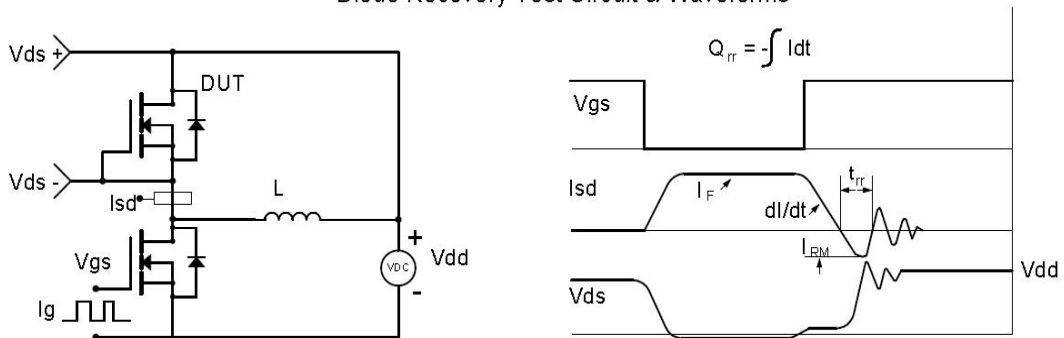
Resistive Switching Test Circuit & Waveforms



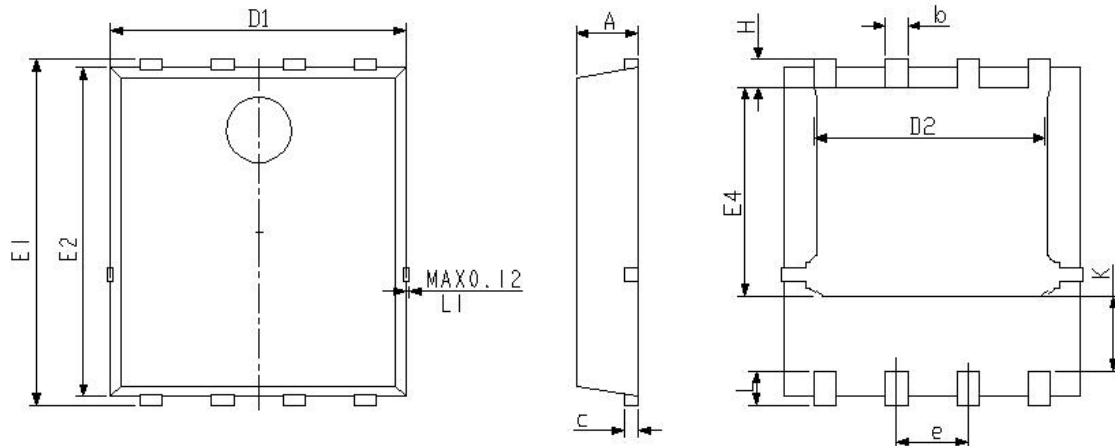
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Mechanical Dimensions for DFN5×6



DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES	
SYMBOL	MIN	MAX	MIN	MAX
A	0.85	1.20	0.033	0.047
b	0.30	0.51	0.012	0.020
c	0.15	0.35	0.006	0.014
D1	4.80	5.40	0.189	0.213
D2	3.70	4.55	0.146	0.179
E1	5.95	6.35	0.234	0.250
E2	5.45	6.06	0.215	0.239
E4	3.30	3.92	0.130	0.154
e	1.27BSC		0.05BSC	
L	0.3	0.71	0.012	0.028
H	0.38	0.71	0.015	0.028
K	1.15	1.45	0.045	0.057

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